



40V N-Channel Enhancement Mode MOSFET

Voltage

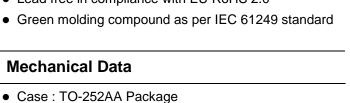
40 V

Current

80 A

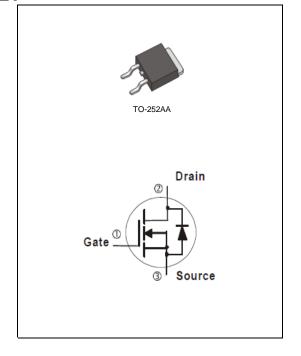
Features

- $R_{DS(ON)}$, $V_{GS}@10V$, $I_D@20A<5.5m\Omega$
- $R_{DS(ON)}$, $V_{GS}@4.5V$, $I_D@10A<7.5m\Omega$
- High switching speed
- Improved dv/dt capability
- Low Gate Charge
- Low reverse transfer capacitance
- Lead free in compliance with EU RoHS 2.0



• Terminals : Solderable per MIL-STD-750, Method 2026

• Weight: 0.0104 ounces, 0.297grams



Maximum Ratings and Thermal Characteristics (T_A=25 °C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V_{DS}	40		
Gate-Source Voltage		V_{GS}	<u>+</u> 20		
Continuous Drain Current	T _C =25°C	I _D	80	A	
	T _C =100°C		50		
Pulsed Drain Current (Note 1)	T _C =25°C	I _{DM}	240		
Power Dissipation	T _C =25°C	PD	66	W	
	T _C =100°C		26.4	VV	
Continuous Drain Current	T _A =25°C	I _D	14		
	T _A =70°C		11	A	
Power Dissipation	T _A =25°C	D-	2.0	W	
Power Dissipation	T _A =70°C	Po	1.3		
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55~150	°C	
Typical Thermal Resistance (Note 4,5)	Junction to Case	$R_{ heta JC}$	1.89	°C/W	
	Junction to Ambient	$R_{\theta JA}$	62.5		

• Limited only By Maximum Junction Temperature





Electrical Characteristics (T_A=25 °C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	40	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} , I _D =250uA	1	1.7	2.5	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =20A	-	4.5	5.5	mΩ
		V _{GS} =4.5V, I _D =10A	-	6	7.5	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} =0V	-	-	1	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} = <u>+</u> 20V, V _{DS} =0V	-	-	<u>+</u> 100	nA
Dynamic (Note 6)						
Total Gate Charge	Qg	V _{DS} =32V, I _D =10A, V _{GS} =4.5V (Note 2,3)	-	25	-	nC
Gate-Source Charge	Q _{gs}		-	7	-	
Gate-Drain Charge	Q _{gd}		-	10	-	
Input Capacitance	Ciss	V _{DS} =25V, V _{GS} =0V, f=1.0MHZ	-	1258	-	pF
Output Capacitance	Coss		-	134	-	
Reverse Transfer Capacitance	Crss	I=1.UIVIHZ	-	88	-	
Turn-On Delay Time	td _(on)	V_{DS} =20V, I_{D} =1A, V_{GS} =10V, R_{G} =3.3 Ω (Note 2,3)	-	18	-	ns
Turn-On Rise Time	t _r		-	13	-	
Turn-Off Delay Time	td _(off)		-	109	-	
Turn-Off Fall Time	t _f		-	73	-	
Drain-Source Diode						
Maximum Continuous Drain-Source					90	А
Diode Forward Current	I _S		-	-	80	
Diode Forward Voltage	V_{SD}	I _S =1A, V _{GS} =0V	-	0.7	1	V

NOTES:

- 1. Pulse width<a>300us, Duty cycle<a>2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C. Ratings are based on low frequency and duty cycles to keep initial T_J =25°C.
- 4. The maximum current rating is package limited.
- 5. Rejah is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz.square pad of copper.
- 6. Guaranteed by design, not subject to production testing.





TYPICAL CHARACTERISTIC CURVES

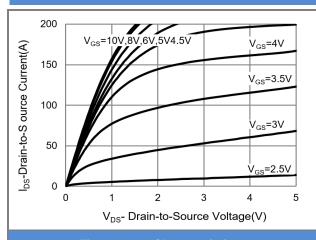


Fig.1 Output Characteristics

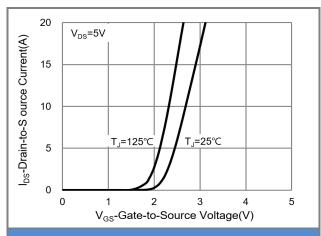


Fig.2 Transfer Characteristics

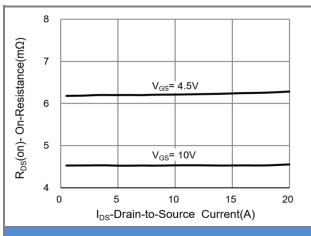


Fig.3 On-Resistance vs. Drain Current

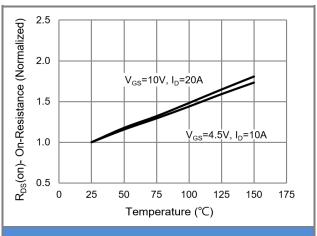


Fig.4 On-Resistance vs. Junction temperature

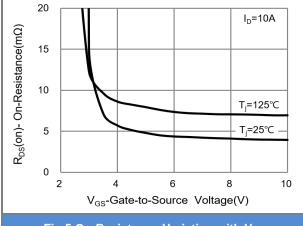


Fig.5 On-Resistance Variation with V_{GS}

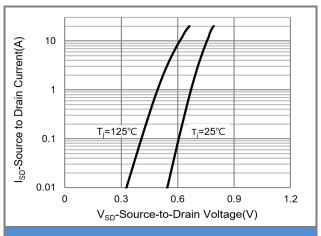


Fig.6 Source-Drain Diode Forward Voltage





TYPICAL CHARACTERISTIC CURVES

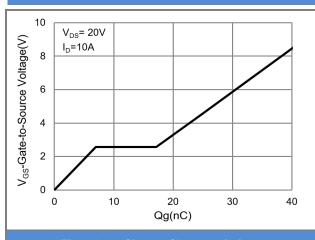


Fig.7 Gate-Charge Characteristics

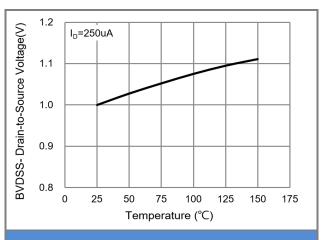


Fig.8 Breakdown Voltage Variation vs. Temperature

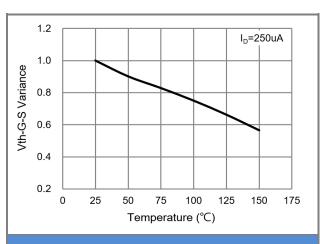


Fig.9 Threshold Voltage Variation with Temperature

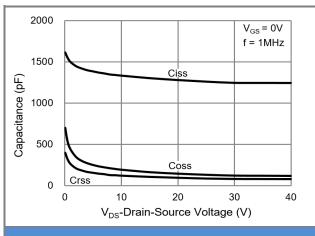
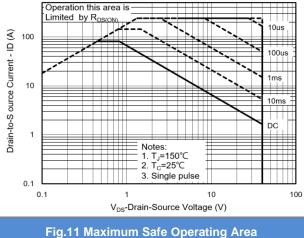


Fig.10 Capacitance vs. Drain-Source Voltage



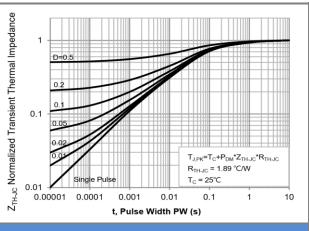


Fig.12 Normalized Transient Thermal Impedance

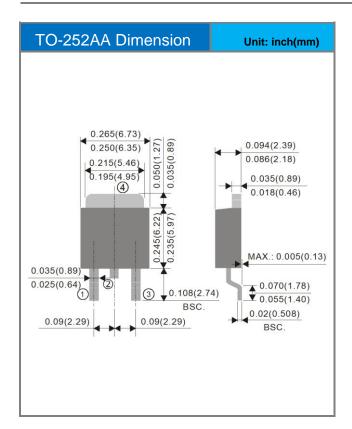


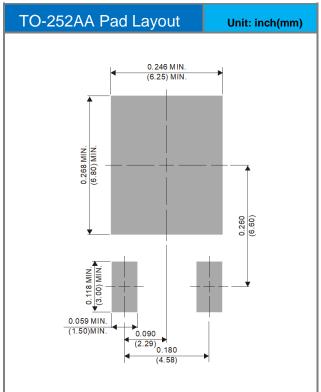


Part No Packing Code Version

Part No Packing Code	Package Type	Packing Type	Marking	Version
PJD80N04_L2_00001	TO-252AA	3,000pcs / 13" reel	D80N04	Halogen free

Packaging Information & Mounting Pad Layout









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